

List of Current Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1 - 8 (Cancelled).

9. (Currently Amended) A device, comprising:
an electronics housing, which defines a first wall and an internal space;
at least one circuit board, which is arranged in the internal space and which is populated at least on a first surface with electronic components, with said first surface directly facing said first wall and said internal space being filled with a potting compound at least between said first surface and said first wall, whereby heat given-off by said electronic components can be led-away to said first wall; and

an area ~~heat~~ heat spreader embedded in the potting compound between said at least one circuit board and said first wall, said heat spreader has a front face and a rear face, which faces said first wall with its front face and said circuit board with its rear face, and which has a greater thermal conductivity than the potting compound, whereby inhomogeneous temperature distributions over the surface of said first wall can be reduced.

10. (Previously presented) The device as claimed in claim 9, wherein:
said heat spreader comprises a metal or ceramic layer, foil.

11. (Previously presented) The device as claimed in claim 10, wherein:
said heat spreader comprises copper or aluminum nitride.

12. (Currently Amended) The device as claimed in claim 10, wherein;
said heat spreader has a thickness of the metal or ceramic sheet of not more than 1 mm~~[,]~~ ~~preferably not more than 0.4 mm, and especially preferably between 0.05~~

~~mm and 0.2 mm.~~

13. (Previously presented) The device as claimed in claim 10, wherein: said heat spreader is essentially planar.

Claims 14 and 15 (Cancelled).

16. (Previously presented) The device as claimed in claim 10, wherein: the device is a measurement transmitter, especially for explosion-protected applications.

17. (New) The device as claimed in claim 10, wherein: said heat spreader has a thickness of the metal or ceramic sheet of not more than 0.4 mm.

18. (New) The device as claimed in claim 10, wherein: said heat spreader has a thickness of the metal or ceramic of between 0.05 mm and 0.2 mm.